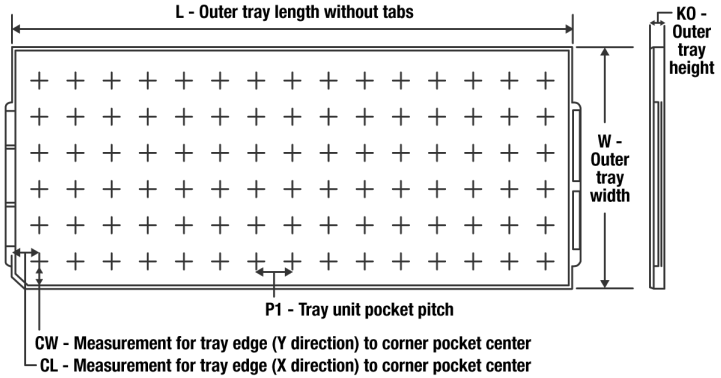
Carrier Material Report for TMS320DM8167SCYG2

Tray Information:



Device	Package Drawing	Package Type	Pins	SPQ	Unit Array Matrix	Max Temp (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
TMS320 DM8167 SCYG2	CYG	FCBGA	1031	44	4X11	150	315	135.9	7620	27.5	20	26.7

Images above are just a representation of the carrier. Actual carrier may vary. Please reference the dimensions provided in the table.

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